



IEEE



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Delft Technical University
Delft, Netherlands

INTERNATIONAL WORKSHOP ON INTEGRATED POWER PACKAGING 2017 CALL FOR PAPERS

The purpose of this workshop is to bring together researchers in the field of power electronics components, electrical insulating materials, and packaging technologies to rapidly promote the development and commercialization of high-density and high-efficiency power converters. Papers ranging from core material technologies to power converters are sought that address important challenges and present solutions to increase reliability and manufacturability of power electronic components and systems while targeting increased performance and reduced system cost. Papers are solicited in the following topics:

- System Integration And Optimization
- Compact Converter Design Techniques
- Modeling & Simulation - Components to Reliability
- Materials & Packaging Technology
- Power Semiconductor Devices / Modules
- Gate/Base Drivers
- Thermal Management & 3D Packaging
- Electromagnetic Interference
- Sensors & Protection
- High-Frequency Magnetics
- High Temperature & High Voltage Dielectrics
- Testing of Electrical Insulating Materials (e.g. Space Charge and Partial Discharge Measurements)
- High-Temperature Capacitors
- Reliability Assessment & Lifetime Prediction
- Functional Safety & Product/Data Sheet Standards
- System/Component Design for Manufacturability, Compatibility with Standards, and Reliability

IWIPP COMMITTEE

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DEADLINES

Abstract Submission: December 2, 2016
Notice of Acceptance: December 30, 2016
Final Paper Submission: February 3, 2017